



## **SPECIFICATION**

• Supplier : Samsung electro-mechanics • Samsung P/N : CL10C151FB8NNWC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 150 pF, 50V, ±1%, C0G, 0603

## A. Samsung Part Number

<u>CL</u> <u>10</u> <u>C</u> <u>151</u> <u>F</u> <u>B</u> <u>8</u> <u>N</u> <u>N</u> <u>W</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor							
2	Size	0603 (inch co	ode) L: 1.6	± 0.1	mm	W:	8.0	± 0.1	mm
3	Dielectric	COG	8	Inner el	ectrode		Ni		
4	Capacitance	<b>150</b> pF		Termina	ation		Cu		
(5)	Capacitance	±1 %		Plating			Sn 10	0%	(Pb Free)
	tolerance		9	Produc	t		Norm	al	
6	Rated Voltage	50 V	10	Special			Produ	ict for N	letwork application
7	Thickness	$0.8 \pm 0.1$	mm (1)	Packag	ing		Cardb	oard T	ype,7"reel(4,000ea)

## **B. Samsung Reliability Test and Judgement condition**

	Performance	Test condition					
Capacitance	Within specified tolerance	1Mb±10% 0.5~5Vrms					
Q	1000 min						
Insulation	More than 500Mohm⋅μF	Rated Voltage 60~120 sec.					
Resistance							
Appearance	No abnormal exterior appearance	Visual inspection					
Withstanding	No dielectric breakdown or	300% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	COG						
Characteristics	(From -55℃ to 125℃, Capacitance change should be within ±30PPM/℃)						
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change: within ±5%	Bending to the limit (1mm)					
		with 1.0mm/sec.					
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder					
	is to be soldered newly	245±5℃, 3±0.3sec.					
		(preheating: 80~120°C for 10~30sec.)					
Resistance to	Capacitance change: within ±2.5%	Solder pot : 270±5℃, 10±1sec.					
Soldering heat	Tan δ, IR : initial spec.						

	Performance	Test condition				
Vibration Test	Capacitance change: within ±2.5%	Amplitude: 1.5mm				
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)				
		2hours × 3 direction (x, y, z)				
Moisture	Capacitance change: within ±7.5%	With rated voltage				
Resistance	Q: 200 min	40±2℃, 90~95%RH, 500 +12/-0 hours				
	IR : More than 25№ μF					
High Temperature	Capacitance change: within ±3%	With 200% of the rated voltage				
Resistance	Q: 350 min	Max. operating temperature				
	IR : More than 50MΩ-μF	1000+48/-0 hours				
Temperature	Capacitance change: within ±2.5%	1 cycle condition				
Cycling	Tan δ, IR : initial spec.	Min. operating temperature → 25°C				
		→ Max. operating temperature → 25°C				
		5 cycles test				

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5  $^{\circ}$ C, 10sec. Max )

<sup>\*</sup> For the more detail Specification, Please refer to the Samsung MLCC catalogue.